

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **07221442 A**

(43) Date of publication of application: **18.08.95**

(51) Int. Cl

H05K 3/34
H05K 3/34

(21) Application number: **06028999**

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(22) Date of filing: **31.01.94**

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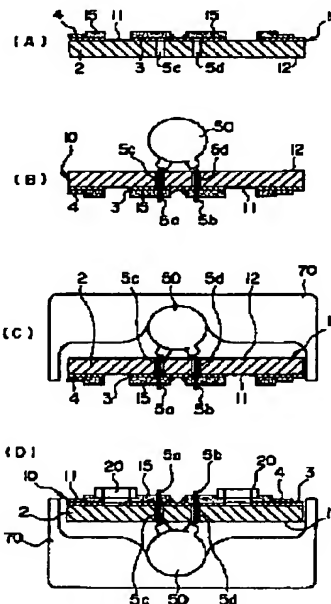
(54) **REFLOW SOLDERING METHOD**

(57) Abstract:

PURPOSE: To reduce manhours, and line equipment, and to reduce heat stress to a part by enabling reflow soldering of a surface mount part, and an insertion part to a substrate simultaneously.

CONSTITUTION: The method includes a process for applying cream solder 15 to one surface 11 of a substrate 10, a process for inserting an insertion part 20 to the substrate 10 from a side of the other surface 12, a process for temporarily fixing the insertion part 20 to the substrate 10 against drop-off, a process for mounting the surface mount part 20 on the substrate 10, and a process for performing reflow soldering for the surface mounting part 20 and the temporarily fixed insertion part 50 simultaneously.

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